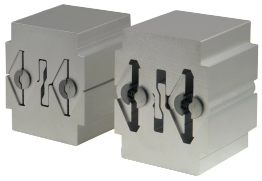
We connect and protect

Interscale Flexible Heat Conductor (FHC), 70 mm

Power Utilities



Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

CERTIFICATIONS

RoHS COMPLIANT

FEATURES

- Designed for ATX/ITX/Mini ITX & COM using Intel core-iprocessors and AMD processors with the following sockets: Intel: LGA775, LGA1150, LGA1155, LGA1156, LGA1366,LGA2011 ; AMD: AM2, AM2(+), AM3, AM3(+), FM1, FM2, FM2(+)
- Compatible with Interscale C enclosures
- Provides industry leading conduction cooling performance, 70% improvement over current conduction cooling methods
- Conductor block expands/contracts vertically to compensate fortolerance stack up and optimizes surface contact and pressurealong the thermal path; eliminates the need for a thermal gappad
- Secured to PCB with mounting brackets, sold separately

SPECIFICATIONS

Table 1/1

Catalog Number	Type	Works With	Package Quantity	Depth	Width

24830-001	Heat Conductor	Cases	1	50 mm	50 mm

ADDITIONAL PRODUCT DETAILS

Please order the mounting bracket (Intel or AMD, listed under accessories) to assemble the FHC to the board.

WARNING

nVent products shall be installed and used only as indicated in nVent's product instruction sheets and training materials. Instruction sheets are available at www.nvent.com and from your nVent customer service representative. Improper installation, misuse, misapplication or other failure to completely follow nVent's instructions and warnings may cause product malfunction, property damage, serious bodily injury and death and/or void your warranty.

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